

JFP MPS Mini-Place-System



The machines which require minimal training to operate

MPS Epoxy Die Bonder

Small Chips & SMD Parts ASSEMBLY



The MPS* fulfil accurate Picking and Placement of delicate devices.

Tool holder design, rocking Head, provides an easy solution for gluing...

Video Interface compatible for Ultra-HD Camera, with adjustable digital magnification for flexibility, small and large chip sizes.

A true vertical motion achieves high accuracy placement combined with a true vertical camera targeting.

A side camera, provide process vision; camera can be tilted at any angle; high magnification zoom capability for very small devices or critical process.

MPS is a robust, and reliable mechanical concept, do not requires any training to operate

• **MPS provides appropriate Platforms for die assembly and small SMD placement**

- Lab and prototype
- Small parts handling capability
- Epoxy dispenser
- Solder paste
- SMD Reflow
- Eutectic die bonding

SYSTEM

- Table Top machine,.
- Compact system
- Z movement: safe manual drive system.
- True Vertical motion
- True vertical Vision, Ultra-HD Camera,
- Soft touch-down
- Throat: 200mm, Access for large substrates

DIE & SUBSTRATE

- Minimum component size: 150*150µm
- Vacuum Tool holders,
- Substrate, size Up to 350 mm
WafflePack, GelPack...

Workholder Stage

- Manually handled
- Fine motion X&Y Stage,
Travel 25x25 mm, resolution 1µm
- Rotary base for easy Theta adjustments
- Work Height : 100mm or 60mm
- Height adjustable workholders
- Working area : 200x200 mm
- Multi-stage: Pick + Place + stamping Disk
- Heated Stages 50mm (solder-Eutectic)
- Hot Gas Option, for SMD Reflow

VISION-ALIGNMENT SYSTEM

- **V5M:** Camera 5MP, Ultra-HD, Zoom
Full Field of view: Up to 11mm
also available FOV=25mm and FOV= 4mm
- PC, vision interface, USB3
- Digital CrossHairs, adjustable
- Adjustable digital video Box
- Adjustable circular video Target
- Adjustable digital Zoom
- LED lightings coaxial and oblique
- Video Overlay, face-Up Chip Placement
- Video Overlay, face-Down Chip Placement
for Optional Flip Placement

FEATURES/PARAMETERS

- Low Picking Force: <10 g
- adjustable Bond Force
- Rocking head, Dipensing/Stamping

APPLICATIONS:

- Lab, Jewelry, Watches, smd, BGA, ...
- Inspection/Process HD Camera
Side view and any angular vision
Zoom: Field of view, FOV= up to 40mm

TECHNICAL SPECIFICATION

Power:	100 / 230VAC 300watt
Vacuum:	integrated
Dimensions:	270*500*352mm
Weight:	17 kg.

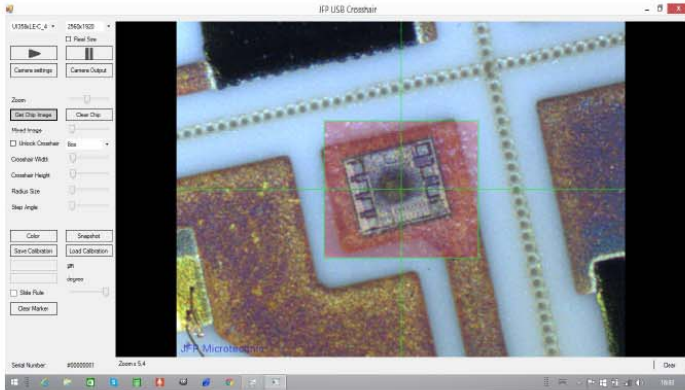
JFP Microtechnic® is a registered trademark

JFP MPS Mini-Place-System



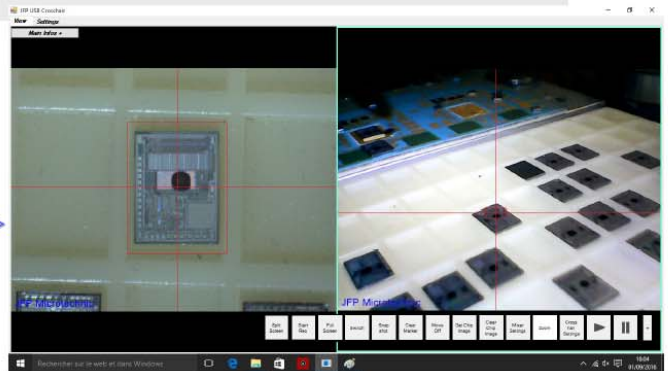
The machines which require minimal training to operate

MPS Options

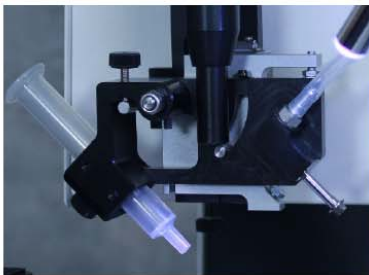


VISION-ALIGNMENT SYSTEM

- **V5M:** Camera 5MP, FULL HD, Zoom
Full Field of view: Up to 11mm
- PC, vision interface, USB3
- Digital CrossHairs, adjustable
- **Overlay** of Face-Up Chip for easy placement
- **Flip Chip Option**
- Overlay of Face-down chip (not shown)

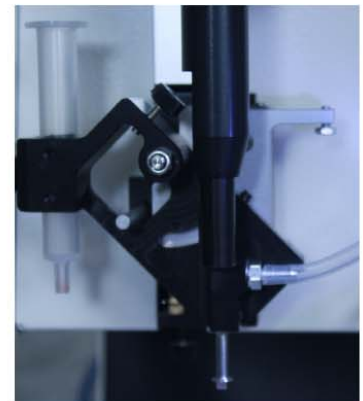


Process Camera >>



Rocking Head

- Dispenser,
- Stamping,
- Pick & Place
- Force Adjustment
- Z movement: soft manual drive system



Work Stages

- Micrometric Table,
Accurate micromotion
Fine Theta adjustments
+ Individual chuck
Adjustable Height
- Heated Chuck 50mm
Reflow, up to 300°C
Adjustable Height



- Multi-WH
- 1 Waffle Pack
 - 2 Place Chuck 2x2", adjustable height
 - 3 Rotary dish for Stamping



JFP Microtechnic® is a registered trademark